



05-25-08

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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Eric NEYRET et al.

Confirmation No.: 1763

Application No: 10/750,443

Group Art Unit: 2818

Filing Date: December 30, 2003

Examiner: Phuc T. Dang

For: METHOD FOR REDUCING FREE SURFACE  
ROUGHNESS OF A SEMICONDUCTOR WAFER

Atty. Docket No.: 4717-8300

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

In response to the Office Action dated May 6, 2005, Applicants respectfully request the entry of the following amendments and comments into the file of this application.

**AMENDMENTS TO THE CLAIMS** begin on page 2.

**REMARKS** begin on page 6.

No fees are believed to be due for this submission. Should any fees be required, however, please charge such fees to Winston & Strawn LLP Deposit Account No. 50-1814.